

ITWS agenda (draft) version 1.03e

Day 1 – Sep. 16, 2024

Start	Session	Duration
13:00	Registration and Coffee & Snacks Service <ul style="list-style-type: none"> Distribution of badges etc. 	45min
13:45	Opening Remarks to the ITWS 2024 <i>Organisational items</i> Speaker: Torsten Liese	15min
Keynote - AI & Wafer Test Data		(Host: TBD)
14:00	Keynote: KAI GmbH, Austria <i>"On The Use Of AI To Identify Patterns In Wafer Test Data"</i> Speaker: Michael Scheiber <ul style="list-style-type: none"> Q & A related to this session 	30min
Session Group A – Wafer Test Data / Increase Test Yields		(Host: TBD)
14:30	1st Session: DELPHON Industries, Inc. California, US <i>"Data Integrity And Device Handling Challenges During Expanded Wafer Test"</i> Speaker: Jerry Broz <ul style="list-style-type: none"> Q & A related to this session 	30min
15:00	2nd Session: HTT High Tech Trade GmbH, Munich, Germany <i>"Increase Test Yields By Reliable OCR Recognition"</i> Speaker: TBD <ul style="list-style-type: none"> Q & A related to this session 	30min
Session Group B – POAA / Potpourri Of New Probe Card Technologies		(Host: Oliver Nagler)
15:30	3rd Session: INFINEON Technologies AG, Munich, Germany <i>"Smart Cantilever Probe Card – Contact Force And AE Crack Risk Analysis Module For Robust Wafer Testing"</i> Speaker: Florian Tremmel & Oliver Nagler <ul style="list-style-type: none"> Q & A related to this session 	30min
16:00	Coffee Break & Poster Sessions	60min
17:00	4th Session: T.I.P.S. Messtechnik GmbH, Villach, Austria <i>"New Vertical Probes For Doubling Current Capability And Better Contact Behaviour"</i> Speaker: Georg Franz <ul style="list-style-type: none"> Q & A related to this session 	30min
17:30	5th Session: Exaddon, Switzerland <i>"Fine-pitch Testing With μ3D Printed Probes"</i> Speaker: TBD (Wabe W. Koelmans) <ul style="list-style-type: none"> Q & A related to this session 	30min
18:00	6th Session: JENOPTIK Optical Systems GmbH, Jena, Germany <i>"Advances In Direct Probing Solution For Opto-electronic Wafer-Level PIC Testing"</i> Speaker: Christian Karras <ul style="list-style-type: none"> Q & A related to this session 	30min
19:00	Dinner	Open end

Day 2 – Sep. 17, 2024

Start	Session	Duration
Session Group C – New Metrology Concepts For Wafer Test (Host: Harald Berger)		
9:30	7th Session: Robert BOSCH GmbH, Reutlingen, Germany <i>“Wafer Warpage Measurement – A Low Cost Solution For Characterization In Electrical Wafer Sort”</i> Speaker: Jakob Dürr <ul style="list-style-type: none"> • Q & A related to this session 	30min
10:00	8th Session: Solarius Europe, Munich, Germany <i>“Introducing A Next Generation Probe Card Metrology Tool To Monitor The Mechanical State Of A Probe Card During The Lifecycle”</i> Speaker: Martin Kunz <ul style="list-style-type: none"> • Q & A related to this session 	30min
10:30	Coffee Break & Poster Sessions	45min
Session Group D – Solutions For Probing of High Power Devices & Temp. Test (Host: Rainer Gaggl)		
11:15	9th Session: T.I.P.S. Messtechnik GmbH, Villach, Austria <i>“Known Good Die – Best Practice For Probing High Power Devices”</i> Speaker: Sebastian Salbrechter <ul style="list-style-type: none"> • Q & A related to this session 	30min
11:45	10th Session: Probe Test Solutions Ltd., Glasgow, UK <i>“High Voltage And High Site Count Testing Using Paschen’ Law”</i> Speaker: Don Thompson Q & A related to this session	30min
12:15	11th Session: SEMICS, Gwangju-si, Korea <i>“Obstacles And Challenges On Economic Automotive Burn-In Process”</i> Speaker: TBD <ul style="list-style-type: none"> • Q & A related to this session 	30min
12:45	12th Session: ERS Electronic GmbH, Germering, Germany <i>“Probing The Limits: Temperature Wafer Test Solutions For Next-Generation Semiconductor Devices”</i> Speaker: Klemens Reitingner <ul style="list-style-type: none"> • Q & A related to this session 	30min
13:15	Summary & of ITWS 2024 Speaker: Torsten Liese	15min
13:30	End of Workshop	

Poster Sessions:

Probe Test Solutions Ltd., Glasgow, UK

“RF Testing From The Lab To The Fab”

MJC Europe GmbH, Munich, Germany

(...to give an overview over the latest MEMS product itself as well as sharing first high-volume MEMS-V manufacturing test results...)

Sigma Sensors (TCL) GmbH, Sigmaringen, Germany

(...SIGMA SENSORS (Temperature Calibration Laboratories) GmbH has been manufacturing and calibrating Temperature Calibration Wafers for Thermal Chucks in Waferprobers since 2009 ...)

SweepMe! GmbH, Dresden, Germany

“Modularized Python Based Software Framework For Control Of Wafer Probers”

JEM Europe + INFINEON Technologies AG, Munich, Germany

“XP5 Probe Material To Address Challenging Probing Requirements”